

SOT2026-1

FBGA957, fine-pitch ball grid array package; 957 terminals,
0.65 mm pitch, 21 mm x 21 mm x 2.16 mm body

10 July 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	FBGA957
Package style descriptive code	FBGA (fine-pitch ball grid array)
Mounting method type	S (surface mount)
Issue date	03-06-2019
Manufacturer package code	98ASA01451D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	21	-	mm
package width	-	21	-	mm
seated height	-	2.16	-	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	957	-	



2 Package outline

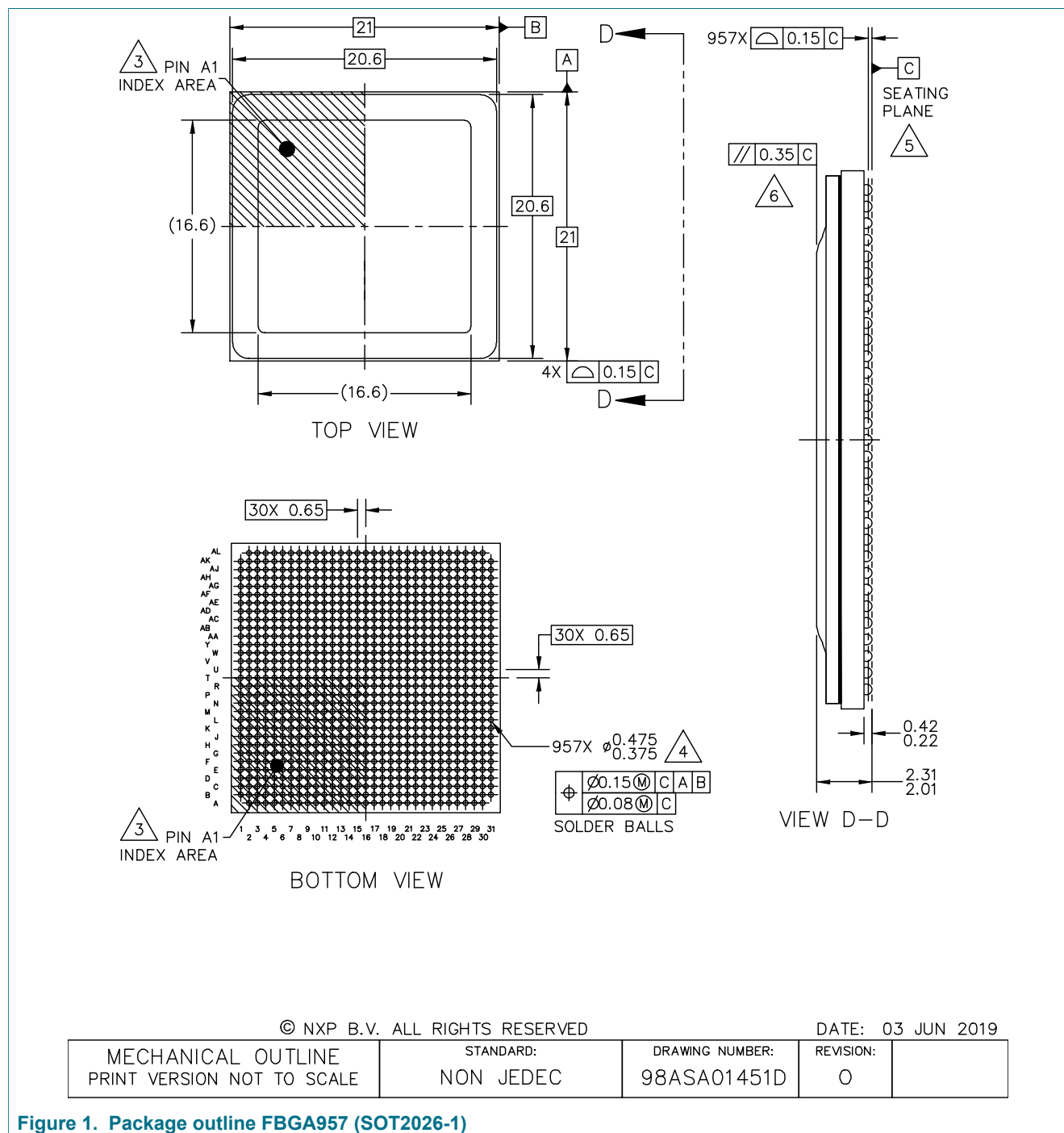
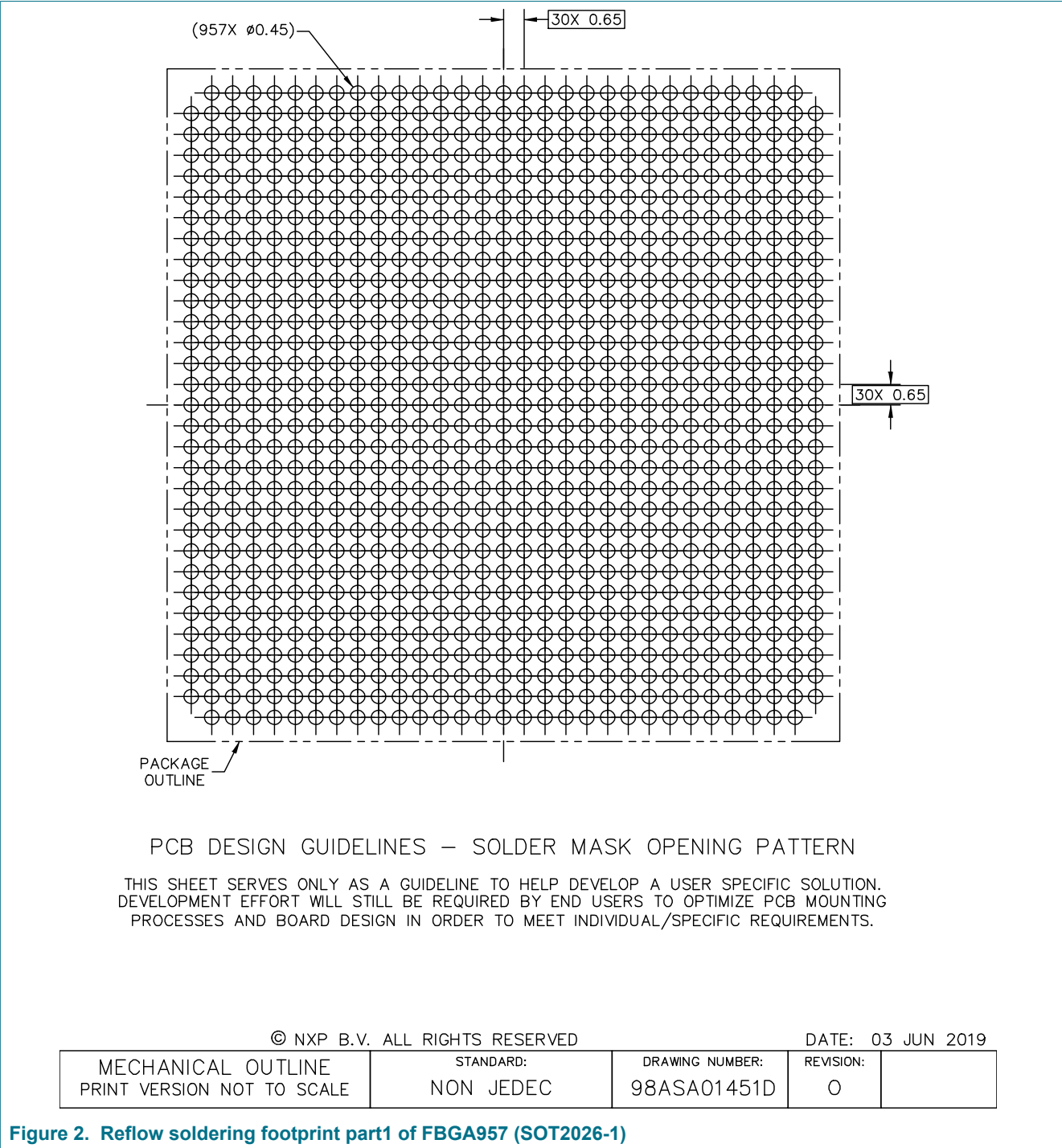


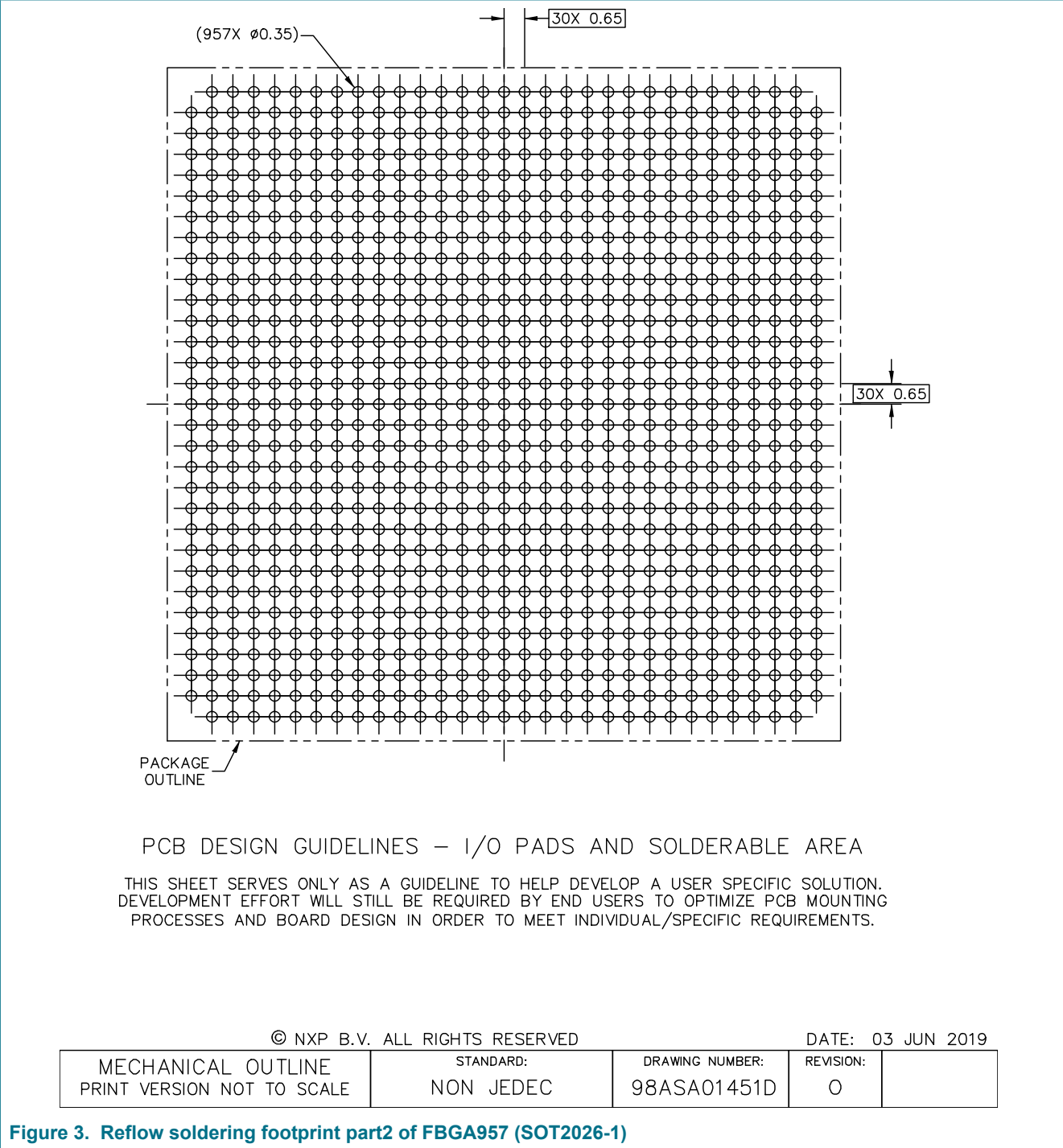
Figure 1. Package outline FBGA957 (SOT2026-1)

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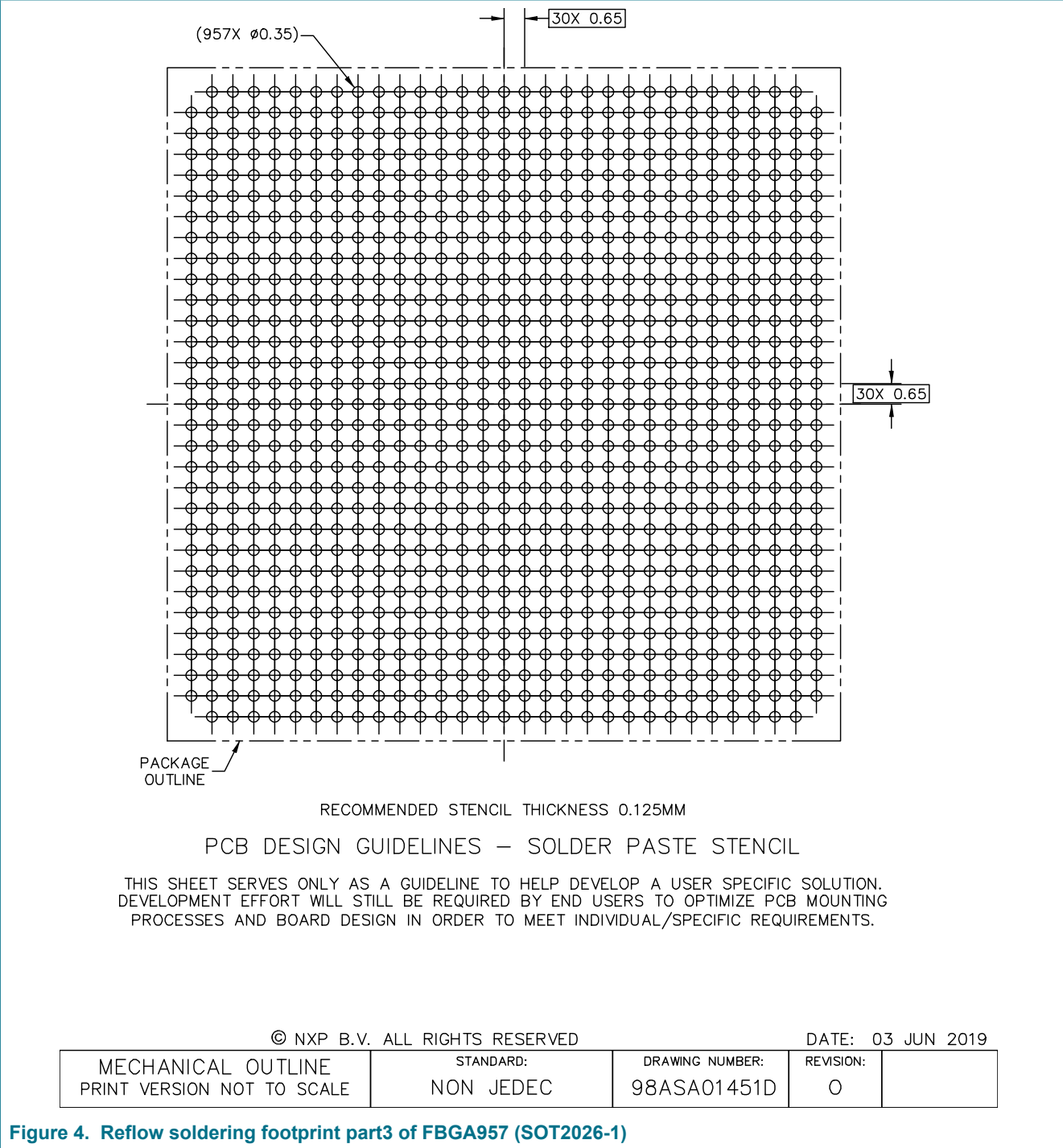
3 Soldering



FBGA957, fine-pitch ball grid array package; 957 terminals, 0.65 mm pitch, 21 mm x 21 mm x 2.16 mm body



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- NOTES:
- 1. ALL DIMENSIONS IN MILLIMETERS.
 - 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
 - 3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
 - 4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
 - 5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 - 6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
 - 7. LID OVERHANG ON SUBSTRATE NOT ALLOWED.

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MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01451D	REVISION: 0	

Figure 5. Package outline note FBGA957 (SOT2026-1)

4 Legal information

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